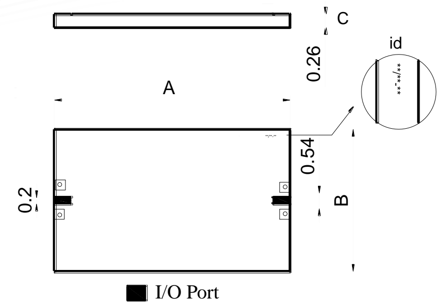
Product Datasheet
Product ID: BMBP221-6PA

EC MICROWAVE
The door to the RF world

Thin Film ceramic Filte

BMBP221-6PA



Precautions

1. The chip is recommended sub-cavity use, both sides of the side wall from about 0.2mm, surface distance Cover about 3mm, the chip ports are interchangeable;

2. Chip recommended low-stress conductive adhesive (such as ME8456) bonding;

3. Chip should be installed in Kovar (recommended) or molybdenum copper with ceramic thermal expansion coefficient(6.7ppm / ℃) on the carrier, the carrier thickness ≥ 0.2mm;

4 circuit board micro-chip wire bonding connection, it is recommended microstrip bonding at mining T-type structure to match, T-size as right

Circuit boardRogers 5880，10mil	Circuit boardRogers 4350，10mi l
0.25 / 0.43 / 0.78 / 0.63 / 1.87	0.29 / 0.31 / 1.3 / 1.55 / 0.66
frequency: DC-38GHz	frequency: DC-32GHz

Features

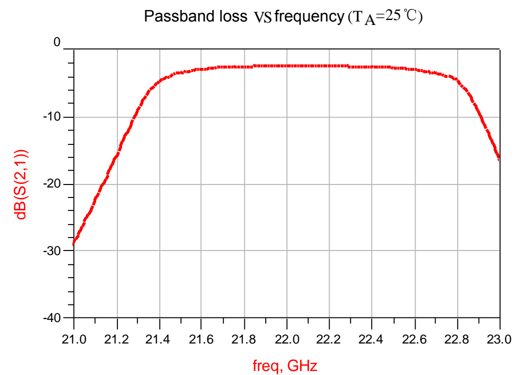
high-precision film processing technology
high performance, low temperature drift, high power
Ceramic substrate, 50Ω coplanar waveguide output
Gold wire bonding, suitable for multi-chip integrated module applications

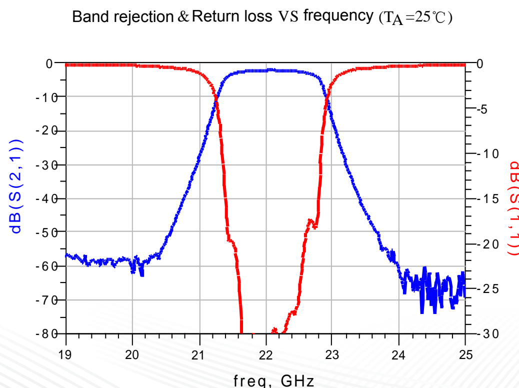
Environmental parameters

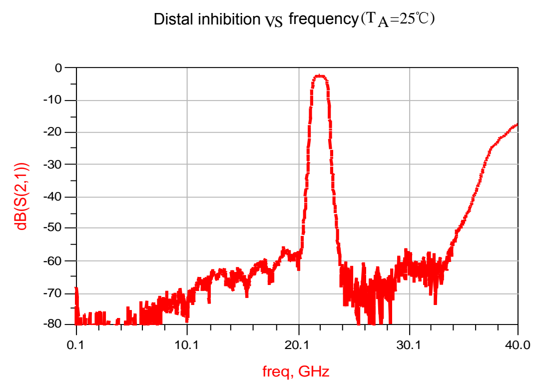
Working temperature	-55℃~+85℃
storage temperature	-55℃~+125℃
Maximum input power	35dBm

Electrical Specifications

Center frequency(f0)	22
Passband frequency range (GHz)	21.5-22.5
Band fluctuations (dB)	1.2
Center insertion loss (dB)	3
Return loss (dB)	16
Band attenuation (dB)	≥ 40@20.6GHz ≥ 40@23.6GHz







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